

MOUNTED CIRCUIT SUBSTRATE AND METHOD FOR FABRICATING  
THE SAME FOR SURFACE LAYER PADS THAT CAN WITHSTAND  
PAD EROSION BY MOLTEN SOLDER APPLIED OVER  
A PLURALITY OF TIMES

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ABSTRACT OF THE DISCLOSURE

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A mounted circuit substrate has at least one  
conductive layer. The side faces of a component mounting  
pad is formed on a surface of the substrate, and includes  
at least a columnar pattern made of a metal highly  
15 resistant to erosion by solder. The side faces of the  
component mounting pad are completely covered with an  
organic insulating layer. Therefore, the component  
mounting pad can withstand molten solder stresses  
accompanying component replacement even when component  
20 replacement is done many times.